

FEATURES

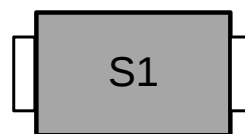
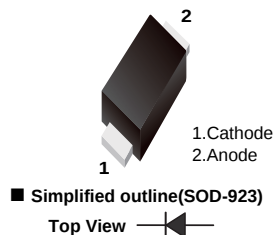
Low current rectification
Low VF
High reliability.
Silicon epitaxial planar

VOLTAGE RANGE

30 Volts

CURRENT

100mA



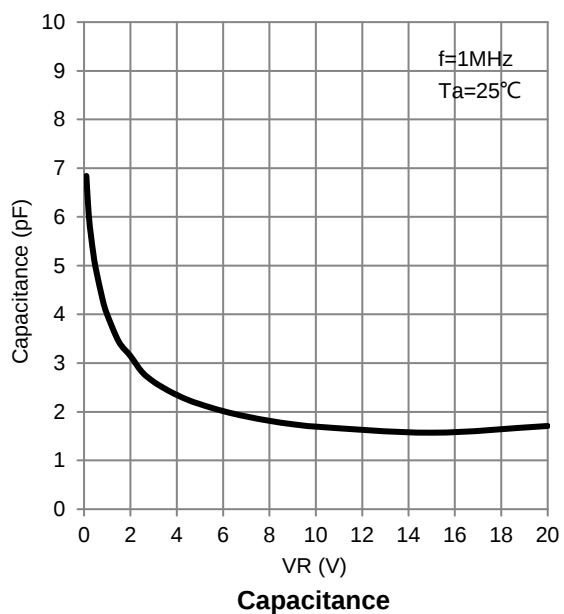
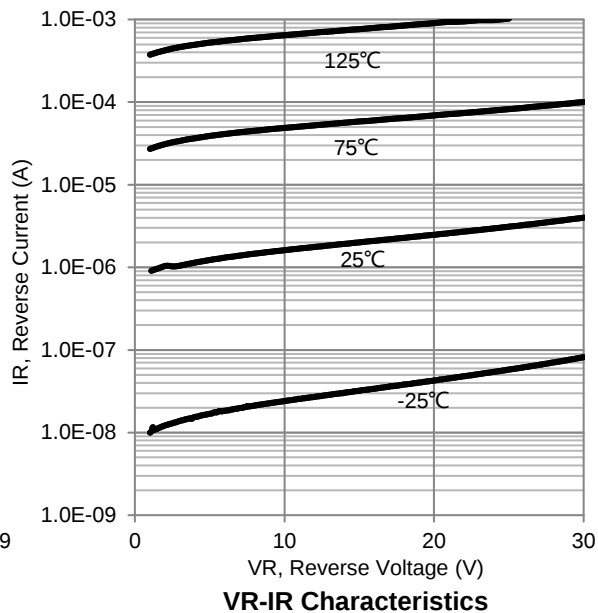
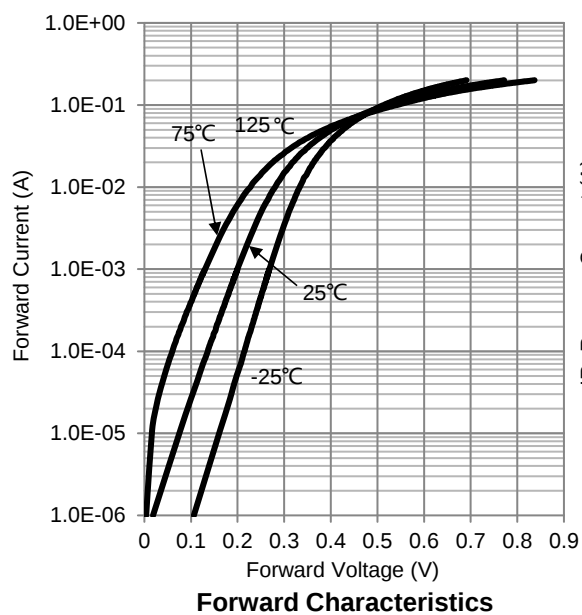
MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

Parameter	Symbol	Limits	Unit
DC reverse voltage	VR	30	V
Average rectifierd forward current	IO	100	mA
Forward current surge peak(60Hz · 1cyc)	IFSM	500	mA
Junction temperature	Tj	125	°C
Storage temperature	Tstg	-40~+125	°C

Characteristics at Ta = 25°C

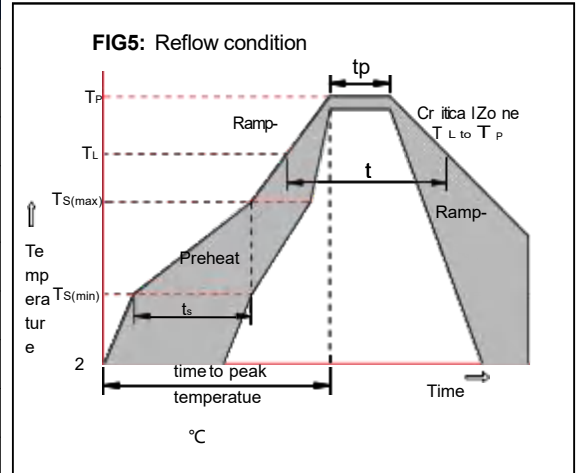
Characteristic	Symbol	Min.	Typ.	Max.	Unit
Forward voltage (IF =10mA)	VF	-	-	0.35	V
(IF =20mA)		-	-	0.4	
Reverse current (VR =10V)	IR	-	-	10	μA

RATING AND CHARACTERISTIC CURVES



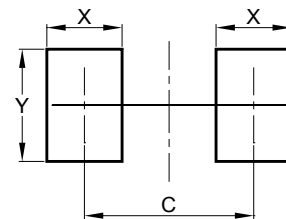
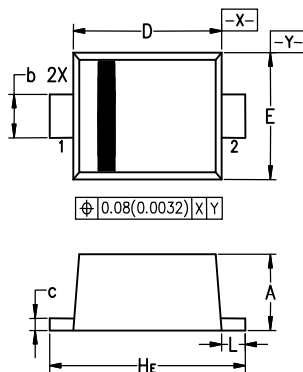
Soldering parameters

Reflow Condition		Pb-Free assembly (see as below)
Pre Heat	-Temperature Min ($T_{s(min)}$)	+150 °C
	-Temperature Max($T_{s(max)}$)	+200 °C
	-Time (Min to Max) (ts)	60-180 secs.
Average ramp up rate (Liquid us Temp (T_L) to peak)		3 °C/sec. Max
$T_{s(max)}$ to T_L - Ramp-up Rate		3 °C/sec. Max
Reflow	-Temperature(T_L)(Liquid us)	+217 °C
	-Temperature(t_L)	60-150 secs.
Peak Temp (T_P)		+260(+0/-5) °C
Time within 5 °C of actual Peak Temp (t_P)		30 secs. Max
Ramp-down Rate		6 °C/sec. Max
Time 25 °C to Peak Temp (T_P)		8 min. Max
Do not exceed		+260 °C



Package Dimensions & Suggested Pad Layout

SOD-923



Dim	Millimeters			Inches		
	Min	Nom	Max	Min	Nom	Max
A	0.36	0.40	0.43	0.014	0.016	0.017
b	0.15	0.20	0.25	0.006	0.008	0.010
c	0.07	0.12	0.17	0.003	0.005	0.007
D	0.75	0.80	0.85	0.030	0.031	0.033
E	0.55	0.60	0.65	0.022	0.024	0.026
Hc	0.95	1.00	1.05	0.037	0.039	0.041
L	0.05	0.10	0.15	0.002	0.004	0.006

Dimensions	Value (in mm)
C	0.950
X	0.450
Y	0.600